	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1553	257/784.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1501	257/786.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	1441	257/777.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	1673	257/686.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	1897	257/773.ccls.	US-PGPUB; USPAT; USOCR
6	BRS	L6	1740	257/723.ccls.	US-PGPUB; USPAT; USOCR
7	BRS	L8	84	L2 and pad and wire and first adj (chip or die)	US-PGPUB; USPAT; USOCR
8	BRS	L9	316	L3 and pad and wire and first adj (chip or die)	US-PGPUB; USPAT; USOCR
9	BRS	L10	302	L4 and pad and wire and first adj (chip or die)	US-PGPUB; USPAT; USOCR

10	BRS	L12	238	L6 and pad and wire and first adj (chip or die)	US-PGPUB; USPAT; USOCR
11	BRS	L11	33	L5 and pad and wire and first adj (chip or die)	US-PGPUB; USPAT; USOCR

	Type	L #	Hits	Search Text	DBs
12	BRS	L7	140	L1 and pad and wire and first adj (chip or die)	US-PGPUB; USPAT; USOCR
13	BRS	L13	825	(bonding adj pad) and wire and first adj (chip or die) and (substrate or board)	US-PGPUB; USPAT; USOCR
14	BRS	L14	777585	L13 and second (chip or die)	US-PGPUB; USPAT; USOCR
15	BRS	L15	603	L13 and second adj (chip or die)	US-PGPUB; USPAT; USOCR
16	BRS	L16	453	257/784.ccls.	EPO; JPO; IBM_TDB
17	BRS	L17	356	257/786.ccls.	EPO; JPO; IBM_TDB
18	BRS	L18	134	257/777.ccls.	EPO; JPO; IBM_TDB
19	BRS	L19	449	257/773.ccls.	EPO; JPO; IBM_TDB